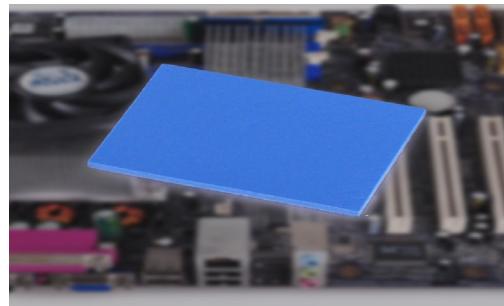


Silicone-free Thermally Conductive Gap Filler Pad

TP300-H50-SF is a silicone-free thermally conductive gap filler pad for high electrical insulation, excellent thermal conductivity and electrical insulation. It can work stably at -40°C~125°C and meet UL94 V-0 flame retardant grade.



Features

- 3.0 W/(m·K) thermal conductivity
- Silicone-free
- High compression
- Naturally adhesive on both side
- High electrical insulation
- Easy to assemble and reusable

Typical Applications

- Fiber Optic Modules
- Medical Equipment
- Optical precision equipment
- Silicone sensitive components
- Control Modules

Typical Properties		
Properties	Attribute	Test Method
Color	Blue	Visual
Thickness(mm)	0.75 to 4.0	ASTM D374
Density(g/cc)	3.0	ASTM D792
Hardness(Shore 00)	50	ASTM D2240
Weight Damnify(%)	≤1.0	Filter paper adsorption @25% compression,125°C,48h
Usage Temperature(°C)	- 40 to 125	/
Flammability	V-0	UL 94
Shelf Life(month)	12	Temperature <40°C avoid extrusion and exposure to the sun
Electrical		
Breakdown Voltage(kV/mm)	≥6.0	ASTM D149
Volume Resistivity(Ω·cm)	5×10 ¹¹	ASTM D257
Dielectric Constant	10.14	ASTM D150
Thermal		
Thermal conductivity(W/(m·K))	3.0	ASTM D5470

Any information provided in this document is considered accurate. All specifications are subject to change without notice. All products and services are sold under the terms and conditions of sale. Neither the seller nor the manufacturer is liable for any direct, incidental or consequential loss or damage to the infringement or contract, including loss of profits or income resulting from the use or inability to use the product. Unless the seller and the manufacturer's official sign the agreement, the seller or the purchaser's statement, purchase order or advice not included here shall have no effect or effect. © Copyright 2019, AOCHUAN TECHNOLOGY.

